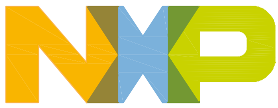



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| TITLE: 360 CBGA 25 X 25, 1.27 PITCH 6 CAPS | DOCUMENT NO: 98ARS10522D REV: C |
| | STANDARD: NON-JEDEC |
| | SOT1603-5 04 JAN 2016 |

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. DIMENSION b IS THE MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. D2 AMD E2 DEFINE THE AREA OCCUPIED BY THE DIE AND UNDERFILL. ACTUAL SIZE OF THIS AREA MAY BE SMALLER THAN SHOWN. D3 AND E3 ARE THE MINIMUM CLEARANCE FROM THE PACKAGE EDGE TO THE CHIP CAPACITORS.

6. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.

7. CAUTION MUST BE TAKEN NOT TO SHORT EXPOSED METAL CAPACITOR PADS ON PACKAGE TOP.

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